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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	32
Number of Logic Elements/Cells	256
Total RAM Bits	-
Number of I/O	78
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo256c-3t100i

June 2013

Data Sheet DS1002

Features

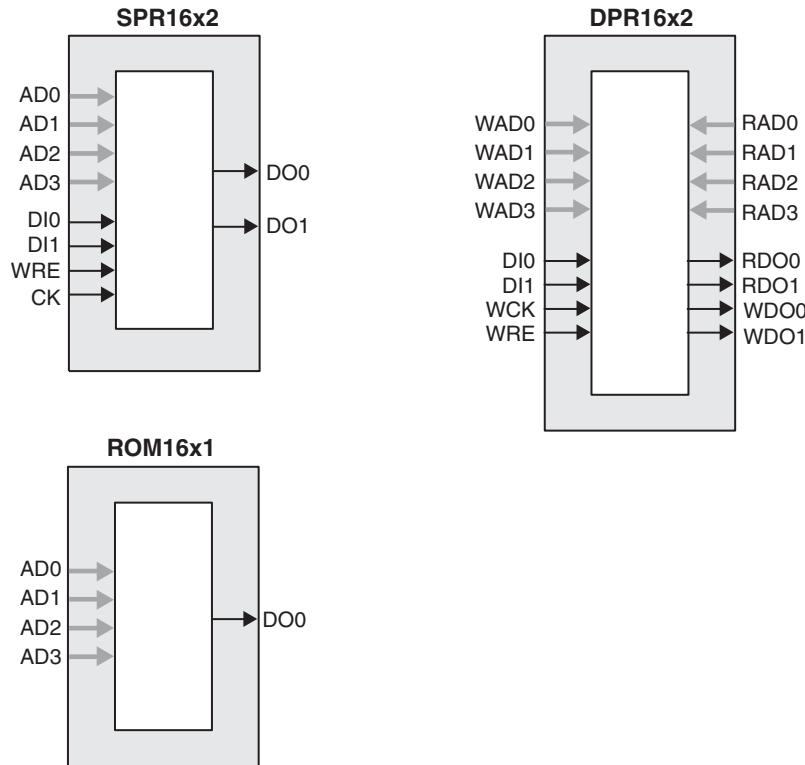
- **Non-volatile, Infinitely Reconfigurable**
 - Instant-on – powers up in microseconds
 - Single chip, no external configuration memory required
 - Excellent design security, no bit stream to intercept
 - Reconfigure SRAM based logic in milliseconds
 - SRAM and non-volatile memory programmable through JTAG port
 - Supports background programming of non-volatile memory
- **Sleep Mode**
 - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
 - In-field logic update while system operates
- **High I/O to Logic Density**
 - 256 to 2280 LUT4s
 - 73 to 271 I/Os with extensive package options
 - Density migration supported
 - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
 - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
 - Up to 7.7 Kbits distributed RAM
 - Dedicated FIFO control logic

Table 1-1. MachXO Family Selection Guide

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

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Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from PLL output, clock net, routing/external pin or internal feedback from CLKINTFB port
RST	I	"1" to reset the input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
CLKINTFB	O	Internal feedback source, CLKOP divider output before CLOCKTREE
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

sysMEM Memory

The MachXO1200 and MachXO2280 devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

PIO Groups

On the MachXO devices, PIO cells are assembled into two different types of PIO groups, those with four PIO cells and those with six PIO cells. PIO groups with four IOs are placed on the left and right sides of the device while PIO groups with six IOs are placed on the top and bottom. The individual PIO cells are connected to their respective sysIO buffers and PADs.

On all MachXO devices, two adjacent PIOs can be joined to provide a complementary Output driver pair. The I/O pin pairs are labeled as "T" and "C" to distinguish between the true and complement pins.

The MachXO1200 and MachXO2280 devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. In addition, half of the PIO pairs on the left and right sides of these devices can be configured as LVDS transmit/receive pairs. PIOs on the top of these larger devices also provide PCI support.

Figure 2-15. Group of Four Programmable I/O Cells

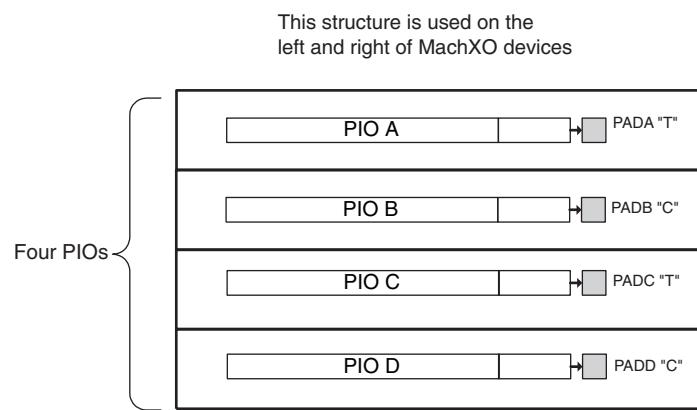
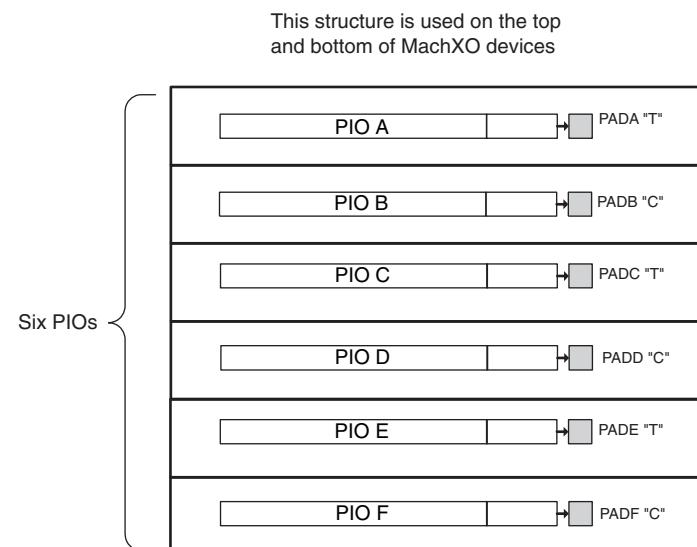


Figure 2-16. Group of Six Programmable I/O Cells



PIO

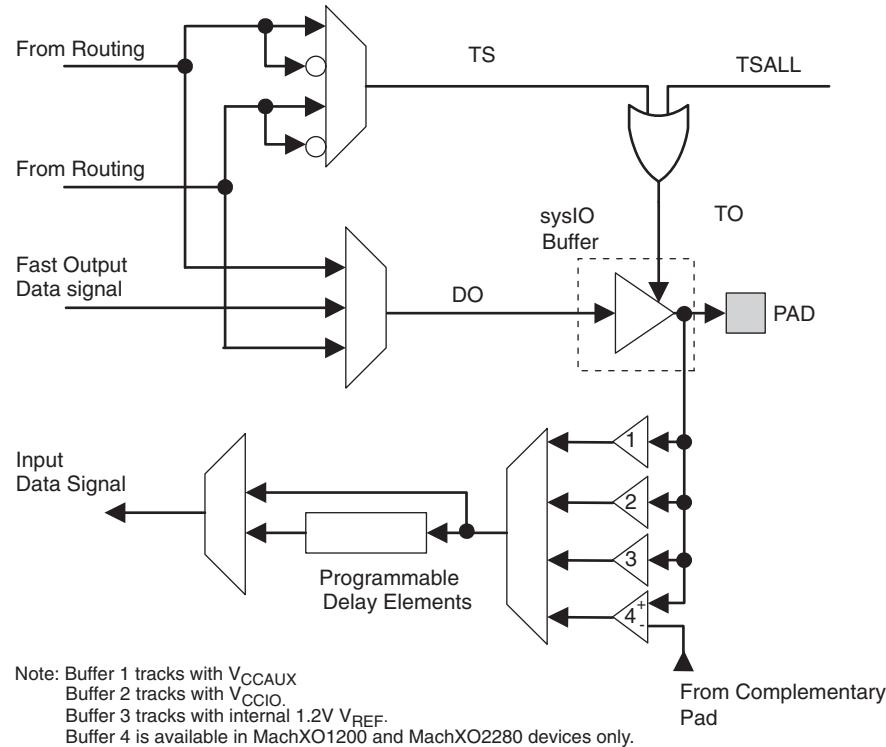
The PIO blocks provide the interface between the sysIO buffers and the internal PFU array blocks. These blocks receive output data from the PFU array and a fast output data signal from adjacent PFUs. The output data and fast

output data signals are multiplexed and provide a single signal to the I/O pin via the sysIO buffer. Figure 2-17 shows the MachXO PIO logic.

The tristate control signal is multiplexed from the output data signals and their complements. In addition a global signal (TSALL) from a dedicated pad can be used to tristate the sysIO buffer.

The PIO receives an input signal from the pin via the sysIO buffer and provides this signal to the core of the device. In addition there are programmable elements that can be utilized by the design tools to avoid positive hold times.

Figure 2-17. MachXO PIO Block Diagram



sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, TTL, BLVDS, LVDS and LVPECL.

In the MachXO devices, single-ended output buffers and ratioed input buffers (LVTTI, LVCMOS and PCI) are powered using V_{CCIO}. In addition to the Bank V_{CCIO} supplies, the MachXO devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that powers up a variety of internal circuits including all the differential and referenced input buffers.

MachXO256 and MachXO640 devices contain single-ended input buffers and single-ended output buffers with complementary outputs on all the I/O Banks.

MachXO1200 and MachXO2280 devices contain two types of sysIO buffer pairs.

1. Top and Bottom sysIO Buffer Pairs

The sysIO buffer pairs in the top and bottom Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (for ratioed or absolute input levels). The I/O pairs on the top and bottom

the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO "C" devices ($V_{CC} = 1.8/2.5/3.3V$) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static I_{CC}	Typical <10mA	0	Typical <100uA
I/O Leakage	<10 μ A	<1mA	<10 μ A
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1} ; MachXO640: V_{CCIO2} ; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.



MachXO Family Data Sheet

DC and Switching Characteristics

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Absolute Maximum Ratings^{1, 2, 3}

	LCMXO E (1.2V)	LCMXO C (1.8V/2.5V/3.3V)
Supply Voltage V _{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V _{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V _{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied ⁴	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied ⁴	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (ambient).....	-65 to 150°C	-65 to 150°C
Junction Temp. (T _j)	+125°C	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions¹

Symbol	Parameter	Min.	Max.	Units
V _{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V _{CCAUX} ³	Auxiliary Supply Voltage	3.135	3.465	V
V _{CCIO} ²	I/O Driver Supply Voltage	1.14	3.465	V
t _{TJCOM}	Junction Temperature Commercial Operation	0	+85	°C
t _{TJIND}	Junction Temperature Industrial Operation	-40	100	°C
t _{TFLASHCOM}	Junction Temperature, Flash Programming, Commercial	0	+85	°C
t _{TFLASHIND}	Junction Temperature, Flash Programming, Industrial	-40	100	°C

1. Like power supplies must be tied together. For example, if V_{CCIO} and V_{CC} are both 2.5V, they must also be the same supply. 3.3V V_{CCIO} and 1.2V V_{CCIO} should be tied to V_{CCAUX} or 1.2V V_{CC} respectively.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CC} must reach minimum V_{CC} value before V_{CCAUX} reaches 2.5V.

MachXO Programming/Erase Specifications

Symbol	Parameter	Min.	Max.	Units
N _{PROGCYC}	Flash Programming Cycles per t _{RETENTION}		1,000	Cycles
	Flash Functional Programming Cycles		10,000	Cycles
t _{RETENTION}	Data Retention at 125° Junction Temperature	10		Years

Supply Current (Sleep Mode)^{1,2}

Symbol	Parameter	Device	Typ. ³	Max.	Units
I_{CC}	Core Power Supply	LCMxo256C	12	25	μA
		LCMxo640C	12	25	μA
		LCMxo1200C	12	25	μA
		LCMxo2280C	12	25	μA
I_{CCAUX}	Auxiliary Power Supply	LCMxo256C	1	15	μA
		LCMxo640C	1	25	μA
		LCMxo1200C	1	45	μA
		LCMxo2280C	1	85	μA
I_{CCIO}	Bank Power Supply ⁴	All LCMxo 'C' Devices	2	30	μA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency = 0MHz.

3. $T_A = 25^\circ C$, power supplies at nominal voltage.

4. Per Bank.

Supply Current (Standby)^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply	LCMxo256C	7	mA
		LCMxo640C	9	mA
		LCMxo1200C	14	mA
		LCMxo2280C	20	mA
		LCMxo256E	4	mA
		LCMxo640E	6	mA
		LCMxo1200E	10	mA
		LCMxo2280E	12	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMxo256E/C	5	mA
		LCMxo640E/C	7	mA
		LCMxo1200E/C	12	mA
		LCMxo2280E/C	13	mA
I_{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.

3. Frequency = 0MHz.

4. User pattern = blank.

5. $T_J = 25^\circ C$, power supplies at nominal voltage.

6. Per Bank. $V_{CCIO} = 2.5V$. Does not include pull-up/pull-down.

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f_{VCO}	PLL VCO Frequency		420	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4 ^{5, 6}	18	25	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected ³	45	55	%
t_{PH}^4	Output Phase Accuracy		—	0.05	UI
t_{OPJIT}^1	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-120	ps
		$f_{OUT} < 100$ MHz	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t_W	Output Clock Pulse Width	At 90% or 10% ³	1	—	ns
t_{LOCK}^2	PLL Lock-in Time		—	150	μs
t_{PA}	Programmable Delay Unit		100	450	ps
t_{IPJIT}	Input Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	+/-200	ps
		$f_{OUT} < 100$ MHz	—	0.02	UI
t_{FBKDLY}	External Feedback Delay		—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. CLKOS as compared to CLKOP output.

5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.

6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

Rev. A 0.19

Pin Information Summary

Pin Type	LCMxo256C/E		LCMxo640C/E				
	100 TQFP	100 csBGA	100 TQFP	144 TQFP	100 csBGA	132 csBGA	256 caBGA / 256 ftBGA
Single Ended User I/O	78	78	74	113	74	101	159
Differential Pair User I/O ¹	38	38	17	43	17	42	79
Muxed	6	6	6	6	6	6	6
TAP	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)	5	5	5	5	5	5	5
VCC	2	2	2	4	2	4	4
VCCAUX	1	1	1	2	1	2	2
VCCIO	Bank0	3	3	2	2	2	4
	Bank1	3	3	2	2	2	4
	Bank2	—	—	2	2	2	4
	Bank3	—	—	2	2	2	4
GND	8	8	10	12	10	12	18
NC	0	0	0	0	0	0	52
Single Ended/Differential I/O per Bank	Bank0	41/20	41/20	18/5	29/10	18/5	26/11
	Bank1	37/18	37/18	21/4	30/11	21/4	27/12
	Bank2	—	—	14/2	24/9	14/2	21/9
	Bank3	—	—	21/6	30/13	21/6	27/10
							40/20

1. These devices support emulated LVDS outputs.pLVDS inputs are not supported.

Pin Type	LCMxo1200C/E				LCMxo2280C/E				
	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	324 ftBGA
Single Ended User I/O	73	113	101	211	73	113	101	211	271
Differential Pair User I/O ¹	27	48	42	105	30	47	41	105	134
Muxed	6	6	6	6	6	6	6	6	6
TAP	4	4	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)	5	5	5	5	5	5	5	5	5
VCC	4	4	4	4	2	4	4	4	6
VCCAUX	2	2	2	2	2	2	2	2	2
VCCIO	Bank0	1	1	1	2	1	1	1	2
	Bank1	1	1	1	2	1	1	1	2
	Bank2	1	1	1	2	1	1	1	2
	Bank3	1	1	1	2	1	1	1	2
	Bank4	1	1	1	2	1	1	1	2
	Bank5	1	1	1	2	1	1	1	2
	Bank6	1	1	1	2	1	1	1	2
	Bank7	1	1	1	2	1	1	1	2
GND	8	12	12	18	8	12	12	18	24
NC	0	0	0	0	0	0	0	0	0
Single Ended/Differential I/O per Bank	Bank0	10/3	14/6	13/5	26/13	9/3	13/6	12/5	24/12
	Bank1	8/2	15/7	13/5	28/14	9/3	16/7	14/5	30/15
	Bank2	10/4	15/7	13/6	26/13	10/4	15/7	13/6	26/13
	Bank3	11/5	15/7	14/7	28/14	11/5	15/7	14/7	28/14
	Bank4	8/3	14/5	13/5	27/13	8/3	14/4	13/4	29/14
	Bank5	5/2	10/4	8/2	22/11	5/2	10/4	8/2	20/10
	Bank6	10/3	15/6	13/6	28/14	10/4	15/6	13/6	28/14
	Bank7	11/5	15/6	14/6	26/13	11/5	15/6	14/6	26/13

1. These devices support on-chip LVDS buffers for left and right I/O Banks.

LCMxo256 and LCMxo640 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMxo256				LCMxo640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
43	PB4A	1		T	PB8B	2		
44	PB4B	1		C	PB8C	2		T
45	PB4C	1		T	PB8D	2		C
46	PB4D	1		C	PB9A	2		
47	PB5A	1			PB9C	2		T
48*	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
49	PB5C	1		T	PB9D	2		C
50	PB5D	1		C	PB9F	2		
51	PR9B	0		C	PR11D	1		C
52	PR9A	0		T	PR11B	1		C
53	PR8B	0		C	PR11C	1		T
54	PR8A	0		T	PR11A	1		T
55	PR7D	0		C	PR10D	1		C
56	PR7C	0		T	PR10C	1		T
57	PR7B	0		C	PR10B	1		C
58	PR7A	0		T	PR10A	1		T
59	PR6B	0		C	PR9D	1		
60	VCCIO0	0			VCCIO1	1		
61	PR6A	0		T	PR9B	1		
62	GNDIO0	0			GNDIO1	1		
63	PR5D	0		C	PR7B	1		
64	PR5C	0		T	PR6C	1		
65	PR5B	0		C	PR6B	1		
66	PR5A	0		T	PR5D	1		
67	PR4B	0		C	PR5B	1		
68	PR4A	0		T	PR4D	1		
69	PR3D	0		C	PR4B	1		
70	PR3C	0		T	PR3D	1		
71	PR3B	0		C	PR3B	1		
72	PR3A	0		T	PR2D	1		
73	PR2B	0		C	PR2B	1		
74	VCCIO0	0			VCCIO1	1		
75	GNDIO0	0			GNDIO1	1		
76	PR2A	0		T	PT9F	0		C
77	PT5C	0			PT9E	0		T
78	PT5B	0		C	PT9C	0		
79	PT5A	0		T	PT9A	0		
80	PT4F	0		C	VCCIO0	0		
81	PT4E	0		T	GNDIO0	0		
82	PT4D	0		C	PT7E	0		
83	PT4C	0		T	PT7A	0		
84	GND	-			GND	-		

LCMxo1200 and LCMxo2280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMxo1200				LCMxo2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
82	PT9A	1			PT12C	1		T
83	GND	-			GND	-		
84	PT8B	1		C	PT11B	1		C
85	PT8A	1		T	PT11A	1		T
86	PT7D	1	PCLK1_1****		PT10B	1	PCLK1_1****	
87	PT6F	0	PCLK0_0****		PT9B	1	PCLK1_0****	
88	PT6D	0		C	PT8F	0		C
89	PT6C	0		T	PT8E	0		T
90	VCCAUX	-			VCCAUX	-		
91	VCC	-			VCC	-		
92	PT5B	0			PT6D	0		
93	PT4B	0			PT6F	0		
94	VCCIO0	0			VCCIO0	0		
95	PT3D	0		C	PT4B	0		C
96	PT3C	0		T	PT4A	0		T
97	PT3B	0			PT3B	0		
98	PT2B	0		C	PT2B	0		C
99	PT2A	0		T	PT2A	0		T
100**	GNDIO0 GNDIO7	-			GNDIO0 GNDIO7	-		

*Supports true LVDS outputs.

**Double bonded to the pin.

***NC for "E" devices.

****Primary clock inputs are single-ended.

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
132 csBGA**

LCMxo640					LCMxo1200					LCMxo2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B1	PL2A	3		T	B1	PL2A	7		T	B1	PL2A	7	LUM0_PLLT_FB_A	T
C1	PL2B	3		C	C1	PL3C	7		T	C1	PL3C	7	LUM0_PLLT_IN_A	T
B2	PL2C	3		T	B2	PL2B	7		C	B2	PL2B	7	LUM0_PLLC_FB_A	C
C2	PL2D	3		C	C2	PL4A	7		T*	C2	PL4A	7		T*
C3	PL3A	3		T	C3	PL3D	7		C	C3	PL3D	7	LUM0_PLLC_IN_A	C
D1	PL3B	3		C	D1	PL4B	7		C*	D1	PL4B	7		C*
D3	PL3D	3			D3	PL4C	7			D3	PL4C	7		
E1	GNDIO3	3			E1	GNDIO7	7			E1	GNDIO7	7		
E2	PL5A	3		T	E2	PL6A	7		T*	E2	PL7A	7		T*
E3	PL5B	3	GSRN	C	E3	PL6B	7	GSRN	C*	E3	PL7B	7	GSRN	C*
F2	PL5D	3			F2	PL6D	7			F2	PL7D	7		
F3	PL6B	3			F3	PL7C	7		T	F3	PL9C	7		T
G1	PL6C	3		T	G1	PL7D	7		C	G1	PL9D	7		C
G2	PL6D	3		C	G2	PL8C	7		T	G2	PL10C	7		T
G3	PL7A	3		T	G3	PL8D	7		C	G3	PL10D	7		C
H2	PL7B	3		C	H2	PL10A	6		T*	H2	PL12A	6		T*
H1	PL7C	3			H1	PL10B	6		C*	H1	PL12B	6		C*
H3	VCC	-			H3	VCC	-			H3	VCC	-		
J1	PL8A	3			J1	PL11B	6			J1	PL14D	6		C
J2	PL8C	3	TSALL		J2	PL11C	6	TSALL	T	J2	PL14C	6	TSALL	T
J3	PL9A	3		T	J3	PL11D	6		C	J3	PL14B	6		
K2	PL9B	3		C	K2	PL12A	6		T*	K2	PL15A	6		T*
K1	PL9C	3			K1	PL12B	6		C*	K1	PL15B	6		C*
L2	GNDIO3	3			L2	GNDIO6	6			L2	GNDIO6	6		
L1	PL10A	3		T	L1	PL14A	6	LLM0_PLLT_FB_A	T*	L1	PL17A	6	LLM0_PLLT_FB_A	T*
L3	PL10B	3		C	L3	PL14B	6	LLM0_PLLC_FB_A	C*	L3	PL17B	6	LLM0_PLLC_FB_A	C*
M1	PL11A	3		T	M1	PL15A	6	LLM0_PLLT_IN_A	T*	M1	PL18A	6	LLM0_PLLT_IN_A	T*
N1	PL11B	3		C	N1	PL16A	6		T	N1	PL19A	6		T
M2	PL11C	3		T	M2	PL15B	6	LLM0_PLLC_IN_A	C*	M2	PL18B	6	LLM0_PLLC_IN_A	C*
P1	PL11D	3		C	P1	PL16B	6		C	P1	PL19B	6		C
P2	GNDIO2	2			P2	GNDIO5	5			P2	GNDIO5	5		
P3	TMS	2	TMS		P3	TMS	5	TMS		P3	TMS	5	TMS	
M3	PB2C	2		T	M3	PB2C	5		T	M3	PB2A	5		T
N3	PB2D	2		C	N3	PB2D	5		C	N3	PB2B	5		C
P4	TCK	2	TCK		P4	TCK	5	TCK		P4	TCK	5	TCK	
M4	PB3B	2			M4	PB3B	5			M4	PB3B	5		
N4	PB3C	2		T	N4	PB4A	5		T	N4	PB4A	5		T
P5	PB3D	2		C	P5	PB4B	5		C	P5	PB4B	5		C
N5	TDO	2	TDO		N5	TDO	5	TDO		N5	TDO	5	TDO	
M5	TDI	2	TDI		M5	TDI	5	TDI		M5	TDI	5	TDI	
N6	PB4E	2		T	N6	PB5C	5			N6	PB6C	5		
P6	VCC	-			P6	VCC	-			P6	VCC	-		
M6	PB4F	2		C	M6	PB6A	5			M6	PB8A	5		
P7	VCCAUX	-			P7	VCCAUX	-			P7	VCCAUX	-		
N7	PB5A	2		T	N7	PB6F	5			N7	PB8F	5		
M7	PB5B	2	PCLK2_1***	C	M7	PB7B	4	PCLK4_1***		M7	PB10F	4	PCLK4_1***	
N8	PB5D	2			N8	PB7C	4		T	N8	PB10C	4		T
P8	PB6A	2		T	P8	PB7D	4		C	P8	PB10D	4		C
M8	PB6B	2	PCLK2_0***	C	M8	PB7F	4	PCLK4_0***		M8	PB10B	4	PCLK4_0***	
N9	PB7A	2		T	N9	PB9A	4		T	N9	PB12A	4		T

**LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections:
 132 csBGA (Cont.)**

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
M9	PB7B	2		C	M9	PB9B	4		C	M9	PB12B	4		C
N10	PB7E	2		T	N10	PB9C	4		T	N10	PB12C	4		T
P10	PB7F	2		C	P10	PB9D	4		C	P10	PB12D	4		C
N11	GNDIO2	2			N11	GNDIO4	4			N11	GNDIO4	4		
P11	PB8C	2		T	P11	PB10A	4		T	P11	PB13C	4		T
M11	PB8D	2		C	M11	PB10B	4		C	M11	PB13D	4		C
P12	PB9C	2		T	P12	PB10C	4			P12	PB15B	4		
P13	PB9D	2		C	P13	PB11C	4		T	P13	PB16C	4		T
N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN	
P14	PB9F	2			P14	PB11D	4		C	P14	PB16D	4		C
N14	PR11D	1		C	N14	PR16B	3		C	N14	PR19B	3		C
M14	PR11C	1		T	M14	PR15B	3		C*	M14	PR18B	3		C*
N13	PR11B	1		C	N13	PR16A	3		T	N13	PR19A	3		T
M12	PR11A	1		T	M12	PR15A	3		T*	M12	PR18A	3		T*
M13	PR10B	1		C	M13	PR14B	3		C*	M13	PR17B	3		C*
L14	PR10A	1		T	L14	PR14A	3		T*	L14	PR17A	3		T*
L13	GNDIO1	1			L13	GNDIO3	3			L13	GNDIO3	3		
K14	PR8D	1		C	K14	PR12B	3		C*	K14	PR15B	3		C*
K13	PR8C	1		T	K13	PR12A	3		T*	K13	PR15A	3		T*
K12	PR8B	1		C	K12	PR11B	3		C*	K12	PR14B	3		C*
J13	PR8A	1		T	J13	PR11A	3		T*	J13	PR14A	3		T*
J12	PR7C	1			J12	PR10B	3		C*	J12	PR13B	3		C*
H14	PR7B	1		C	H14	PR10A	3		T*	H14	PR13A	3		T*
H13	PR7A	1		T	H13	PR9B	3		C*	H13	PR11B	3		C*
H12	PR6D	1		C	H12	PR9A	3		T*	H12	PR11A	3		T*
G13	PR6C	1		T	G13	PR8B	2		C*	G13	PR10B	2		C*
G14	PR6B	1			G14	PR8A	2		T*	G14	PR10A	2		T*
G12	VCC	-			G12	VCC	-			G12	VCC	-		
F14	PR5D	1		C	F14	PR6C	2			F14	PR8C	2		
F13	PR5C	1		T	F13	PR6B	2		C*	F13	PR8B	2		C*
F12	PR4D	1		C	F12	PR6A	2		T*	F12	PR8A	2		T*
E13	PR4C	1		T	E13	PR5B	2		C*	E13	PR7B	2		C*
E14	PR4B	1			E14	PR5A	2		T*	E14	PR7A	2		T*
D13	GNDIO1	1			D13	GNDIO2	2			D13	GNDIO2	2		
D14	PR3D	1		C	D14	PR4B	2		C*	D14	PR5B	2		C*
D12	PR3C	1		T	D12	PR4A	2		T*	D12	PR5A	2		T*
C14	PR2D	1		C	C14	PR3D	2		C	C14	PR4D	2		C
B14	PR2C	1		T	B14	PR2B	2		C	B14	PR3B	2		C*
C13	PR2B	1		C	C13	PR3C	2		T	C13	PR4C	2		T
A14	PR2A	1		T	A14	PR2A	2		T	A14	PR3A	2		T*
A13	PT9F	0		C	A13	PT11D	1		C	A13	PT16D	1		C
A12	PT9E	0		T	A12	PT11B	1		C	A12	PT16B	1		C
B13	PT9D	0		C	B13	PT11C	1		T	B13	PT16C	1		T
B12	PT9C	0		T	B12	PT10F	1			B12	PT15D	1		
C12	PT9B	0		C	C12	PT11A	1		T	C12	PT16A	1		T
A11	PT9A	0		T	A11	PT10D	1		C	A11	PT14B	1		C
C11	PT8C	0			C11	PT10C	1		T	C11	PT14A	1		T
A10	GNDIO0	0			A10	GNDIO1	1			A10	GNDIO1	1		
B10	PT7F	0		C	B10	PT9F	1		C	B10	PT12F	1		C
C10	PT7E	0		T	C10	PT9E	1		T	C10	PT12E	1		T

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 256 caBGA / 256 ftBGA**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
E4	NC				E4	PL2A	7		T	E4	PL2A	7	LUM0_PLLT_FB_A	T
E5	NC				E5	PL2B	7		C	E5	PL2B	7	LUM0_PLLC_FB_A	C
F5	NC				F5	PL3A	7		T*	F5	PL3A	7		T*
F6	NC				F6	PL3B	7		C*	F6	PL3B	7		C*
F3	PL3A	3		T	F3	PL3C	7		T	F3	PL3C	7	LUM0_PLLT_IN_A	T
F4	PL3B	3		C	F4	PL3D	7		C	F4	PL3D	7	LUM0_PLLC_IN_A	C
E3	PL2C	3		T	E3	PL4A	7		T*	E3	PL4A	7		T*
E2	PL2D	3		C	E2	PL4B	7		C*	E2	PL4B	7		C*
C3	NC				C3	PL4C	7		T	C3	PL4C	7		T
C2	NC				C2	PL4D	7		C	C2	PL4D	7		C
B1	PL2A	3		T	B1	PL5A	7		T*	B1	PL5A	7		T*
C1	PL2B	3		C	C1	PL5B	7		C*	C1	PL5B	7		C*
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
D2	PL3C	3		T	D2	PL5C	7		T	D2	PL6C	7		T
D1	PL3D	3		C	D1	PL5D	7		C	D1	PL6D	7		C
F2	PL5A	3		T	F2	PL6A	7		T*	F2	PL7A	7		T*
G2	PL5B	3	GSRN	C	G2	PL6B	7	GSRN	C*	G2	PL7B	7	GSRN	C*
E1	PL4A	3		T	E1	PL6C	7		T	E1	PL7C	7		T
F1	PL4B	3		C	F1	PL6D	7		C	F1	PL7D	7		C
G4	NC				G4	PL7A	7		T*	G4	PL8A	7		T*
G5	NC				G5	PL7B	7		C*	G5	PL8B	7		C*
GND	GND	-			GND	GND	-			GND	GND	-		
G3	PL4C	3		T	G3	PL7C	7		T	G3	PL8C	7		T
H3	PL4D	3		C	H3	PL7D	7		C	H3	PL8D	7		C
H4	NC				H4	PL8A	7		T*	H4	PL9A	7		T*
H5	NC				H5	PL8B	7		C*	H5	PL9B	7		C*
-	-				VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
-	-				GND	GNDIO7	7			GND	GNDIO7	7		
G1	PL5C	3		T	G1	PL8C	7		T	G1	PL10C	7		T
H1	PL5D	3		C	H1	PL8D	7		C	H1	PL10D	7		C
H2	PL6A	3		T	H2	PL9A	6		T*	H2	PL11A	6		T*
J2	PL6B	3		C	J2	PL9B	6		C*	J2	PL11B	6		C*
J3	PL7C	3		T	J3	PL9C	6		T	J3	PL11C	6		T
K3	PL7D	3		C	K3	PL9D	6		C	K3	PL11D	6		C
J1	PL6C	3		T	J1	PL10A	6		T*	J1	PL12A	6		T*
-	-				VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
-	-				GND	GNDIO6	6			GND	GNDIO6	6		
K1	PL6D	3		C	K1	PL10B	6		C*	K1	PL12B	6		C*
K2	PL9A	3		T	K2	PL10C	6		T	K2	PL12C	6		T
L2	PL9B	3		C	L2	PL10D	6		C	L2	PL12D	6		C
L1	PL7A	3		T	L1	PL11A	6		T*	L1	PL13A	6		T*
M1	PL7B	3		C	M1	PL11B	6		C*	M1	PL13B	6		C*
P1	PL8D	3		C	P1	PL11D	6		C	P1	PL14D	6		C
N1	PL8C	3	TSALL	T	N1	PL11C	6	TSALL	T	N1	PL14C	6	TSALL	T
L3	PL10A	3		T	L3	PL12A	6		T*	L3	PL15A	6		T*
M3	PL10B	3		C	M3	PL12B	6		C*	M3	PL15B	6		C*
M2	PL9C	3		T	M2	PL12C	6		T	M2	PL15C	6		T
N2	PL9D	3		C	N2	PL12D	6		C	N2	PL15D	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
G2	PL11A	6		T*
H2	PL11B	6		C*
L3	PL11C	6		T
L5	PL11D	6		C
H1	PL12A	6		T*
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
J2	PL12B	6		C*
L4	PL12C	6		T
L6	PL12D	6		C
K2	PL13A	6		T*
K1	PL13B	6		C*
J1	PL13C	6		T
VCC	VCC	-		
L2	PL13D	6		C
M5	PL14D	6		C
M3	PL14C	6	TSALL	T
L1	PL14B	6		C*
M2	PL14A	6		T*
M1	PL15A	6		T*
N1	PL15B	6		C*
M6	PL15C	6		T
M4	PL15D	6		C
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
P1	PL16A	6		T*
P2	PL16B	6		C*
N3	PL16C	6		T
N4	PL16D	6		C
GND	GND	-		
T1	PL17A	6	LLM0_PLLT_FB_A	T*
R1	PL17B	6	LLM0_PLLC_FB_A	C*
P3	PL17C	6		T
N5	PL17D	6		C
R3	PL18A	6	LLM0_PLLT_IN_A	T*
R2	PL18B	6	LLM0_PLLC_IN_A	C*
P4	PL19A	6		T
N6	PL19B	6		C
U1	PL20A	6		T
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		

Lead-Free Packaging
Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3TN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	COM
LCMxo256C-4TN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	COM
LCMxo256C-5TN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free TQFP	100	COM
LCMxo256C-3MN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	COM
LCMxo256C-4MN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	COM
LCMxo256C-5MN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3TN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	COM
LCMxo640C-4TN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	COM
LCMxo640C-5TN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free TQFP	100	COM
LCMxo640C-3MN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	COM
LCMxo640C-4MN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	COM
LCMxo640C-5MN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free csBGA	100	COM
LCMxo640C-3TN144C	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMxo640C-4TN144C	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMxo640C-5TN144C	640	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMxo640C-3MN132C	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMxo640C-4MN132C	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMxo640C-5MN132C	640	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMxo640C-3BN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	COM
LCMxo640C-4BN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	COM
LCMxo640C-5BN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free caBGA	256	COM
LCMxo640C-3FTN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	COM
LCMxo640C-4FTN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	COM
LCMxo640C-5FTN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3TN100C	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMxo1200C-4TN100C	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMxo1200C-5TN100C	1200	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMxo1200C-3TN144C	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMxo1200C-4TN144C	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMxo1200C-5TN144C	1200	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMxo1200C-3MN132C	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMxo1200C-4MN132C	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMxo1200C-5MN132C	1200	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMxo1200C-3BN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMxo1200C-4BN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMxo1200C-5BN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMxo1200C-3FTN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMxo1200C-4FTN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMxo1200C-5FTN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3TN100C	1200	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMxo1200E-4TN100C	1200	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMxo1200E-5TN100C	1200	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMxo1200E-3TN144C	1200	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMxo1200E-4TN144C	1200	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMxo1200E-5TN144C	1200	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMxo1200E-3MN132C	1200	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMxo1200E-4MN132C	1200	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMxo1200E-5MN132C	1200	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMxo1200E-3BN256C	1200	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMxo1200E-4BN256C	1200	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMxo1200E-5BN256C	1200	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMxo1200E-3FTN256C	1200	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMxo1200E-4FTN256C	1200	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMxo1200E-5FTN256C	1200	1.2V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3TN100C	2280	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMxo2280E-4TN100C	2280	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMxo2280E-5TN100C	2280	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMxo2280E-3TN144C	2280	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMxo2280E-4TN144C	2280	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMxo2280E-5TN144C	2280	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMxo2280E-3MN132C	2280	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMxo2280E-4MN132C	2280	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMxo2280E-5MN132C	2280	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMxo2280E-3BN256C	2280	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMxo2280E-4BN256C	2280	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMxo2280E-5BN256C	2280	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMxo2280E-3FTN256C	2280	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMxo2280E-4FTN256C	2280	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMxo2280E-5FTN256C	2280	1.2V	211	-5	Lead-Free ftBGA	256	COM
LCMxo2280E-3FTN324C	2280	1.2V	271	-3	Lead-Free ftBGA	324	COM
LCMxo2280E-4FTN324C	2280	1.2V	271	-4	Lead-Free ftBGA	324	COM
LCMxo2280E-5FTN324C	2280	1.2V	271	-5	Lead-Free ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3TN100I	256	1.2V	78	-3	Lead-Free TQFP	100	IND
LCMxo256E-4TN100I	256	1.2V	78	-4	Lead-Free TQFP	100	IND
LCMxo256E-3MN100I	256	1.2V	78	-3	Lead-Free csBGA	100	IND
LCMxo256E-4MN100I	256	1.2V	78	-4	Lead-Free csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3TN100I	640	1.2V	74	-3	Lead-Free TQFP	100	IND
LCMxo640E-4TN100I	640	1.2V	74	-4	Lead-Free TQFP	100	IND
LCMxo640E-3MN100I	640	1.2V	74	-3	Lead-Free csBGA	100	IND
LCMxo640E-4MN100I	640	1.2V	74	-4	Lead-Free csBGA	100	IND
LCMxo640E-3TN144I	640	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMxo640E-4TN144I	640	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMxo640E-3MN132I	640	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMxo640E-4MN132I	640	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMxo640E-3BN256I	640	1.2V	159	-3	Lead-Free caBGA	256	IND
LCMxo640E-4BN256I	640	1.2V	159	-4	Lead-Free caBGA	256	IND
LCMxo640E-3FTN256I	640	1.2V	159	-3	Lead-Free ftBGA	256	IND
LCMxo640E-4FTN256I	640	1.2V	159	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3TN100I	1200	1.2V	73	-3	Lead-Free TQFP	100	IND
LCMxo1200E-4TN100I	1200	1.2V	73	-4	Lead-Free TQFP	100	IND
LCMxo1200E-3TN144I	1200	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMxo1200E-4TN144I	1200	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMxo1200E-3MN132I	1200	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMxo1200E-4MN132I	1200	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMxo1200E-3BN256I	1200	1.2V	211	-3	Lead-Free caBGA	256	IND
LCMxo1200E-4BN256I	1200	1.2V	211	-4	Lead-Free caBGA	256	IND
LCMxo1200E-3FTN256I	1200	1.2V	211	-3	Lead-Free ftBGA	256	IND
LCMxo1200E-4FTN256I	1200	1.2V	211	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3TN100I	2280	1.2V	73	-3	Lead-Free TQFP	100	IND
LCMxo2280E-4TN100I	2280	1.2V	73	-4	Lead-Free TQFP	100	IND
LCMxo2280E-3TN144I	2280	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMxo2280E-4TN144I	2280	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMxo2280E-3MN132I	2280	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMxo2280E-4MN132I	2280	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMxo2280E-3BN256I	2280	1.2V	211	-3	Lead-Free caBGA	256	IND
LCMxo2280E-4BN256I	2280	1.2V	211	-4	Lead-Free caBGA	256	IND
LCMxo2280E-3FTN256I	2280	1.2V	211	-3	Lead-Free ftBGA	256	IND
LCMxo2280E-4FTN256I	2280	1.2V	211	-4	Lead-Free ftBGA	256	IND
LCMxo2280E-3FTN324I	2280	1.2V	271	-3	Lead-Free ftBGA	324	IND
LCMxo2280E-4FTN324I	2280	1.2V	271	-4	Lead-Free ftBGA	324	IND



MachXO Family Data Sheet

Revision History

June 2013

Data Sheet DS1002

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
		DC and Switching Characteristics	Security section updated.
			Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timingupdated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
		Pinout Information	JTAG Port Timing Specification updated (rev. A 0.16).
			SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	Logic Signal Connection section has been updated to include all devices/packages.
			Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/ LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

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